

Option Information

Optocoupler lead-bend configurations are available as options. In addition, partial discharge testing as per VDE/IEC is also available as an option.

See the order information section in the data sheet to determine if and which options are available to a specific product. Contact the Vishay sales office for other option configurations. The options are:

Option 1 VDE option

Option 6 400 mil (10.16 mm) lead spread DIP configuration

Option 7 Surface mount, gull wing DIP configuration with standoff

Option 8 Surface mount, gull wing DIP configuration with increased clearance

Option 9 Surface mount, gull wing DIP configuration

ORDERING OPTIONS

A specific option or combination of options can be ordered by add the options definition field following the base part number and CTR range (if applicable) as presented in the following example:

S	F	H	6	1	5	A	-	3	X	0	0	9	T
Prefix			Base Part Number				CTR Ranges		Options Definition			Tape and Reel Option	
BRT													Option 1 Optocouplers for safe electrical insulation per DIN VDE 0884
II													Option 6 Optocouplers with 10.16 mm (0.4") through hole lead spread
ILD													Option 7 Optocouplers with SMD lead form bend, 0.9 mm maximum standoff height
ILQ													Option 8 Optocouplers with 10.16 mm (0.4") SMD lead form bend
SFH6													Option 9 Optocouplers with SMD lead form bend, 0.25 mm maximum standoff height
VO													Option 1 may be combined with the other lead forming options.

Examples:
 CNY17F-2X017T
 4N35-X016
 SFH615-3X001
 VO615A-9X007T

Note
 (1) Used on selected products, consult data sheet for details

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This field is always 4 characters long and commences with the character X. In the case of surface mounted products in Tape and Reel format, the tape and reel option character "T" will follow this field. The possible combinations for these Fields (1) are:

X001, X006, X007, X008, X009, X001T (2), X007T, X008T, X009T, X016, X017, X018, X019, X017T, X018T, X019T

Notes

- (1) Not all options are available for all product types.
- (2) The X001T option is only available on products that are available on the following SMD products SFH6106, SFH6156, SFH6186, SFH6206 and SFH6286 series, e.g. SFH6106-3X001T.

OPTION 1 OPTOCOUPERS FOR SAFE ELECTRICAL INSULATION PER DIN EN 60747-5-5 (VDE 0884) (1)

The optocoupler listed are suitable for safe electrical insulation only within the safety maximum ratings. Compliance with the safety maximum ratings must be ensured by protective circuits.

The partial discharge measurement ensures that no partial discharge occurs during operation at maximum permissible operating insulation voltage (V_{IORM}). Permanent partial discharge affects the insulating materials and can result in a high voltage breakdown.

It is recommended that tests with the insulation test voltage (V_{ISOL}) should not be made, otherwise partial discharge may occur impairing the insulation characteristics. Thus partial discharges also may occur at the maximum permissible operating insulation voltage.

The insulation test per DIN EN 60747-5-5 (VDE 0884) is carried out after all the other tests

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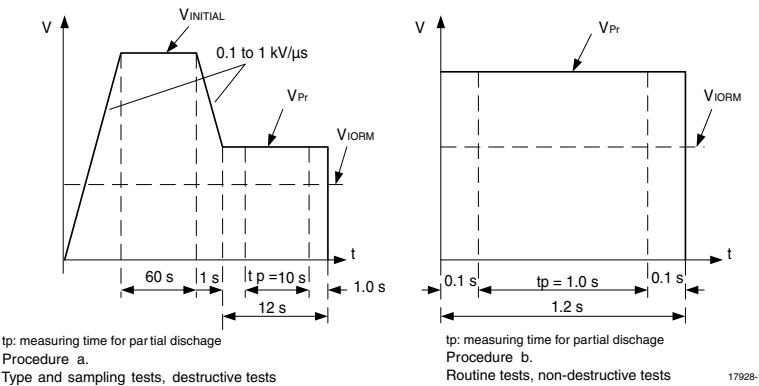


Fig. 1 - Time Voltage Diagram per DIN EN 60747-5-2 (VDE 0884)/DIN EN 60747-5-5 (pending)

DESCRIPTION	SYMBOL	SYSTEM 1			UNIT
		DIP4	DIP8	DIP16	
SFH610A..	SFH610A..	ILCT6		ILQ1/2/5/74	
SFH615A..	SFH615A..	ILD1/2/5/74		ILQ30/31/55	
SFH615AA..	SFH615AA..	ILD30/31/55		ILQ32	
SFH615AGB..	SFH615AGB..	ILD32		ILQ66-..	
SFH615AGR..	SFH615AGR..	ILD66-..		ILQ615-..	
SFH617A..	SFH617A..	ILD250/1/2		ILQ620-..	
SFH618A..	SFH618A..	ILD255		ILQ620GB..	
SFH620A..	SFH620A..	ILD621GB-..		ILQ621-..	
SFH620AA..	SFH620AA..	ILD621-..		ILQ621GB-..	
SFH620AGB..	SFH620AGB..	ILD621GB-..			
SFH628A..	SFH628A..	ILD755-..			
SFH6106..	SFH6106..	ILD766-..			
SFH6116..	SFH6116..	MCT6			
SFH6156..	SFH6156..				
SFH6186..	SFH6186..				
SFH6206..	SFH6206..				
SFH6286..	SFH6286..				
Installation category (DIN VDE 0110)					
For rated line voltages $\leq 300 \text{ V}_{\text{RMS}}$				I - IV	
For rated line voltages $\leq 600 \text{ V}_{\text{RMS}}$				I - IV	
For rated line voltages $\leq 1000 \text{ V}_{\text{RMS}}$					
IEC climatic category (DIN IEC 60068 Part 1/9.80)				55/100/21	
Pollution degree (DIN VDE 0110 Part 1/1.89)				2	
Maximum operation insulating voltage ⁽¹⁾	V_{IORM}			890	V
Test voltage input/output, procedure b ⁽¹⁾ $V_{\text{Pr}} = 1.875 \times V_{\text{IORM}}$, routine 100 % test, $t_p = 1 \text{ s}$, partial discharge < 5 pC	V_{Pr}			1669	V
Test voltage input/output, procedure a ⁽¹⁾ $V_{\text{Pr}} = 1.5 \times V_{\text{IORM}}$, type and sampling test $t_p = 60 \text{ s}$, partial discharge < 5 pC	V_{Pr}			1335	V
Maximum permissible overvoltage (transient overvoltage)	V_{IOTM}			8000	V
Partial discharge test voltage ⁽¹⁾	V_{INITIAL}			8000	V
Safety maximum ratings (maximum permissible ratings in case of a fault, also refer to d diagram) Package temperature Current (input current I_F , $P_{Si} = 0$, $T_A = 25 \text{ }^{\circ}\text{C}$) Derating with higher ambient temperature Power (output or total power dissipation, $T_A = 25 \text{ }^{\circ}\text{C}$) Derating with higher ambient temperature	T_{Si} I_{Si} D_{Si} P_{Si} ΔP_{Si}			175 275 - 1.83 400 - 2.67	$^{\circ}\text{C}$ mA mA/K mW mW/K
Insulation resistance at T_{Si} $V_{I/O} = 500 \text{ V}$	R_{IS}			$> 10^9$	W

DESCRIPTION	SYMBOL	SYSTEM 2		UNIT
		4N25/26/27/28	IL250	MCT5210
		4N35/36/37/38/39	IL251	MCT5211
		4N32/33	IL252	SFH600...
		CNY17-..	IL255-..	SFH601-..
		CNY17F-..	IL400	SFH608-..
		H11A-..	IL755-..	SFH640-..
		H11AA1-..	IL755B-..	MOC8050
		H11B-..	IL766-..	IL56B-..
		H11B1-..	IL766B-..	MOC8021
		H11C-..	MCA230/231	MOC8112
		H11D-..	MCA255	MOC8102/03/04/05
		IL1/2/5/74	MCT2/2E	
		IL2B-..	MCT270/271	
		IL30/31/55	MCT272	
		IL55B-..	MCT273/274	
		IL66-..	MCT275	
		IL66B-..	MCT276/277	
		IL201/202/203		
Installation category (DIN VDE 0110)				
For rated line voltages \leq 300 V _{RMS}		I - IV		
For rated line voltages \leq 600 V _{RMS}		I - IV		
For rated line voltages \leq 1000 V _{RMS}				
IEC climatic category (DIN IEC 60068 Part 1/9.80)		55/100/21		
Pollution degree (DIN VDE 0110 Part 1/1.89)		2		
Maximum operation insulating voltage ⁽¹⁾	V _{IORM}	890		
Test voltage input/output, procedure b ⁽¹⁾ V _{Pr} = 1.875 \times V _{IORM} , routine 100 % test, t _p = 1 s, partial discharge < 5 pC	V _{Pr}	1669		
Test voltage input/output, procedure a ⁽¹⁾ V _{Pr} = 1.5 \times V _{IORM} , type and sampling test t _p = 60 s, partial discharge < 5 pC	V _{Pr}	1335		
Maximum permissible overvoltage (transient overvoltage)	V _{IOTM}	8000		
Partial discharge test voltage ⁽¹⁾	V _{INITIAL}	8000		
Safety maximum ratings (maximum permissible ratings in case of a fault, also refer to diagram) Package temperature Current (input current I _F , P _{Si} = 0, T _A = 25 °C) Derating with higher ambient temperature Power (output or total power dissipation, T _A = 25 °C) Derating with higher ambient temperature	T _{Si} I _{Si} D _{ISi} P _{Si} ΔP _{Si}	175 400 - 2.67 700 - 4.67		
Insulation resistance at T _{Si} V _{I/O} = 500 V	R _{IS}	> 10 ⁹		

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DESCRIPTION	SYMBOL	SYSTEM 4 ⁽²⁾	SYSTEM 5	SYSTEM 7	UNIT
		IL410	6N135	IL300	
		IL420	6N136	IL300E	
		IL4116	SFH6135	IL300F	
		IL4117	SFH6136	IL300EF	
		IL4118	6N138	IL300DEFG	
		IL4216	SFH6138		
		IL4217	SFH6139		
		IL4218	6N139		
			SFH6345		
Installation category (DIN VDE 0110)					
For rated line voltages \leq 300 V _{RMS}		I - IV	I - IV	I - IV	
For rated line voltages \leq 600 V _{RMS}		I - III	I - IV	I - IV	
For rated line voltages \leq 1000 V _{RMS}					
IEC climatic category (DIN IEC 60068 Part 1/9.80)		55/100/21	55/100/21	55/100/21	
Pollution degree (DIN VDE 0110 Part 1/1.89)		2	2	2	
Maximum operation insulating voltage ⁽¹⁾	V _{IORM}	850	630	890	V
Test voltage input/output, procedure b ⁽¹⁾ V _{Pr} = 1.875 \times V _{IORM} , routine 100 % test, t _p = 1 s, partial discharge < 5 pC	V _{Pr}	1594	1181	1669	V
Test voltage input/output, procedure a ⁽¹⁾ V _{Pr} = 1.5 \times V _{IORM} , type and sampling Test t _p = 60 s, partial discharge < 5 pC	V _{Pr}	1275	945	1335	V
Maximum permissible overvoltage (transient overvoltage)	V _{IOTM}	6000	8000	8000	V
Partial discharge test voltage ⁽¹⁾	V _{INITIAL}	6000	8000	8000	V
Safety maximum ratings (maximum permissible ratings in case of a fault, also refer to diagram)					
Package temperature	T _{Si}	175	175	165	°C
Current	I _{Si}	250	300	235	mA
(input current I _F , P _{Si} = 0, T _A = 25 °C)					
Derating with higher ambient temperature	D _{ISi}	- 1.65	- 2	- 1.57	mA/K
Power (output or total power dissipation, T _A = 25 °C)	P _{Si}	500	500	465	mW
Derating with higher ambient temperature	ΔP _{Si}	- 3.33	- 3.33	- 3.1	mW/K
Insulation resistance at T _{Si} V _{I/O} = 500 V	R _{IS}	> 10 ⁹	> 10 ⁹	> 10 ⁹	W

Notes

All voltages referred to are peak values except otherwise specified.

(1) See time-test voltage diagram

(2) In preparation

Testing input/output voltage requires all input pins and all output pins to be shorted

Option 1: Tested per DIN EN 60747-5-2 (VDE 0884)/DIN EN 60747-5-5 (pending)

Option 6: Wide lead spacing (10.16 mm creepage/clearance distances > 8 mm)

Option 7: Surface mount leads (creepage/clearance distances > 8 mm)

Option 8: Surface mount leads

Option 9: Surface mount leads

See CECC 00802, edition 1, for soldering conditions for SMT devices (option 7 and 9).

"-.." means dash selections

OPTION 6

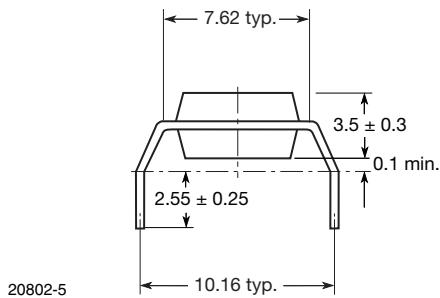
DIP OPTOCOUPERS WITH 0.4" (10.16 mm) LEAD SPREAD

The leads of the optocouplers are bent according to a spacing of 0.4" (10.16 mm). Dimensions deviating from the standard type are:

Lead spacing	10.16 mm (0.4")
Creepage distance	> 8 mm
Clearance	> 8 mm

This version additionally complies with the following standards:

- IEC 60950 DIN VDE 0805/05 90 (System 2 and 3 only)
Reinforced insulation up to an operating voltage of 400 V_{RMS} or DC



Clearance-creepage distance = 8 mm min.
See standard version for pin configuration

OPTION 7

LEAD BENDS FOR SURFACE MOUNT OPTOCOUPERS

These optocouplers are suitable for surface mounting. Dimensions deviating from the standard type are:

Creepage distance > 8 mm
Clearance distance > 8 mm

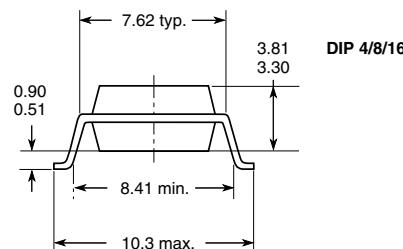
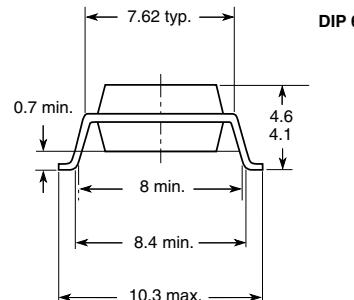
This version additionally complies with the following standards:

- IEC 60950 DIN VDE 0805/05 90 (system 2 and 3 only)
Reinforced insulation up to an operating voltage of 400 V_{RMS} or DC

During the soldering process, the package should not be wetted with tin-lead solder to prevent the impairment of the isolation features. Apart from iron soldering, only reflow soldering methods (vapor phase, infrared and hot gas) are permissible.

Permissible soldering conditions for SMD bending options:
please see reflow soldering profile

The soldering process may be repeated two times at the most. Attention must be paid to the cooling down of the device to 25 °C between the soldering processes.



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Clearance and creepage distances must be considered for the solder pad design.

Clearance-creepage distance = 8 mm min.
See standard version for pin configuration.

OPTION 8

LEAD BENDS FOR SURFACE MOUNT OPTOCOUPERS

These optocouplers are suitable for surface mounting. Dimensions deviating from the standard type are:

Creepage distance > 8 mm
Clearance distance > 8 mm

This version additionally complies with the following standards:

- IEC 60950 DIN VDE 0805/05 90 (system 2 and 3 only)
Reinforced insulation up to an operating voltage of 400 V_{RMS} or DC

During the soldering process, the package should not be wetted with tin-lead solder to prevent the impairment of the isolation features. Apart from iron soldering, only reflow soldering methods (vapor phase, infrared and hot gas) are permissible.

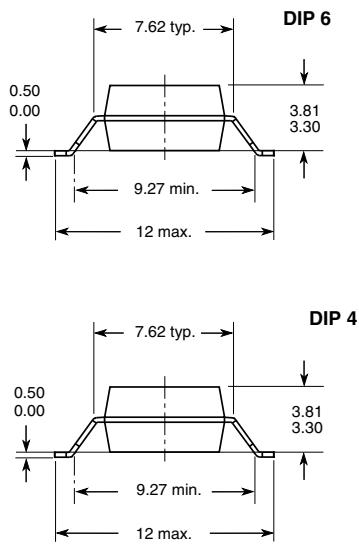
Permissible soldering conditions for SMD bending options:
please see reflow soldering profile

The soldering process may be repeated two times at the most. Attention must be paid to the cooling down of the device to 25 °C between the soldering processes

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Clearance and creepage distances must be considered for the solder pad design.

Clearance-creepage distance = 8 mm min.

See standard version for pin configuration.

OPTION 9 LEAD BENDS FOR SURFACE MOUNT OPTOCOUPERS

During the soldering process, the package should not be wetted with tin-lead solder to prevent the impairment of the isolation features. Apart from iron soldering, only reflow soldering methods (vapor phase, infrared and hot gas) are permissible.

Permissible soldering conditions for SMD bending options:
please see reflow soldering profile

The soldering process may be repeated two times at the most. Attention must be paid to the cooling down of the device to 25 °C between the soldering processes.

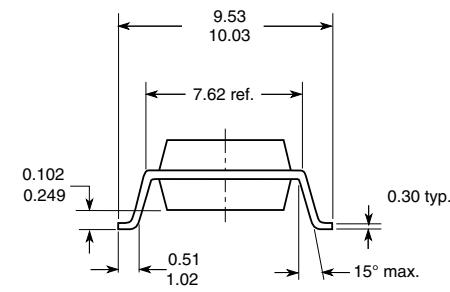
MARKINGS

Product marking is defined in the data sheets. In the cases where marking is not defined in the datasheet, the following table defines the option information that is marked on the product.

OPTION TYPE	MARKING
X001, X001T	X001, X1 (1)
X006	No mark
X007, X007T	X007
X008, X008T	X008
X009, X009T	No mark
X016	X001
X017, X017T	X017
X018, X018T	X018
X019, X019T	X001

Note

(1) X1 is used on the SOP and SOIC-8 where there are space constraints.



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